OTP E 42015

TRANSMITTAL FORM			Application No.	10/81	2,464		
TRANSMITTAL FORM		Filing Date	Marcl	n 29, 2004			
(to be used for all correspondence after initial filing)		First Named Inventor	John l	P. Barnak			
		Art Unit	2823				
			Examiner Name	Willia	nm M. Brewster		
Total Number of f	Total Number of Pages in This Submission 8 Attorney Docket Number 42P19017						
	ENCLOSURES (check all that apply)						
Fee Transmittal	Form	Drawing(s)	€′		After Allowance Communication to Group		
Fee Attac	hed	Licensing-r	elated Papers		Appeal Communication to Board of Appeals and Interferences		
Amendment / R	esponse	Petition			Appeal Communication to Group Appeal Notice, Brlef, Reply Brlef)		
After Fina Affidavits	il /declaration(s)	Petition to 0 Provisional	Convert a Application		Proprietary Information		
Extension of Tir	nè Request	Power of A Change of	ttorney, Revocation Correspondence Address		Status Letter		
Express Abandonment Request		Terminal D	isclaimer		Other Enclosure(s) (please identify below):		
Information Disclosure Statement		Request for	r Refund		Cited Foreign and on-Patent References (5)		
PTO/SB/08		CD, Numbe	er of CD(s)		Return Receipt Postcard		
Certified Copy of Priority Document(s)							
Response to Missing Parts/ Incomplete Application		Remarks					
I =	Filing Fee						
	aration/POA e to Missing						
Parts und 1.52 or 1.	e to Missing er 37 CFR 53						
	SIGNATUR	E OF APPLICA	NT, ATTORNEY, OR A	GENT			
Firm or	Vincent H. And	lerson, Reg. N	o. 54,962				
Individual name BLAKELY, SOKOLOFF, 7			TAYLOR & ZAFI	MAN L	LLP		
Signature Vind HAV							
Date October 26, 2005							
	CERTIF	ICATE OF MAIL	ING/TRANSMISSION				
I hereby certify that this correspondence is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.							
Typed or printed na	me Theresa Bell	and	2				
Signature	Theres	XXXIII	′	Date	October 26, 2005		

OCT 2 8 2005

FEE TRANSMITTAL for FY 2005

Patent fees are subject to annual revision.

Applicant claims small entity status. See 37 CFR 1.27.

TOTAL AMOUNT OF PAYMENT (\$)

Complete if Known					
Application Number	10/812,464				
Filing Date	March 29, 2004				
First Named Inventor	John P. Barnak				
Examiner Name	William M. Brewster				
Art Unit	2823				
Attorney Docket No.	42P19017				

метно	OF PAY	MENT (c	heck all	that apply)				
Check [Credit ca	ard M	oney Or	der None Other (please identify):				
Deposit Account Deposit Account Number: 02-2666 Deposit Account Name: Blakely, Sokoloff, Taylor & Zafman LLP								
☐ Cha ⊠ Cha	For the above-identified deposit account, the Director is hereby authorized to: (check all that apply) Charge fee(s) indicated below Charge any additional fee(s) or underpayment of fee(s) Under 37 CFR §§ 1.16, 1.17, 1.18 and 1.20.							
FEE CALCU	LATION							
Large Er	ntity	Small	Entity		•			
Fee	Fee	Fee	Fee	Fee Description	Fee Paid			
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1051	130	2051	65	Surcharge - late filing fee or oath				
1052	50	2052	25	Surcharge - late provisional filing fee or cover sheet.				
2053	130	2053		Non-English specification				
1251	120	2251		Extension for reply within first month				
1252	450	2252		Extension for reply within second month				
1253	1,020	2253		Extension for reply within third month				
1254	1,590	2254		Extension for reply within fourth month				
1255	2,160	2255		Extension for reply within fifth month				
1401	500	2401		Notice of Appeal				
1402	500	2402		Filing a brief in support of an appeal				
1403	1,000	2403		Request for oral hearing				
1451	1,510	2451		Petition to institute a public use proceeding				
1460	130	2460		Petitions to the Commissioner				
1807	50	1807		Processing fee under 37 CFR 1.17(q)				
1806	180	1806		Submission of Information Disclosure Stmt				
1809	790	1809		Filing a submission after final rejection (37 CFR § 1.129(a))				
1810	790	2810		For each additional invention to be examined (37 CFR § 1.129(b))				
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SUBMITTED E	BY			Comp	lete (if applicable)
Name (Print/Type)	Vincent H. Anderson	Registration No. (Attorney/Agent)	54,962	Telephone	(503) 439-8778
Signature	VarthAh			Date	10/26/05

Docket No.: 42P19017

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re the Application of:

JOHN P. BARNAK, ET AL.

Application No.: 10/812,464

Filed: March 29, 2004

For: UNDER BUMP METALLIZATION LAYER TO

ENABLE USE OF HIGH TIN CONTENT SOLDER

BUMPS

Art Group: 2823

Examiner: William M. Brewster

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In accordance with the duty of disclosure, enclosed is a copy of IDS Citation Form PTO/SB/08 or PTO-1449, together with copies of the documents cited on that form, except for copies not required to be submitted (e.g., copies of U.S. patents and U.S. published patent applications need not be enclosed). This IDS and IDS Citation Form are being submitted before the mailing of a final Office Action. It is respectfully requested that the cited references be considered and that the enclosed copy of PTO/SB/08 be initialed by the Examiner to indicate such consideration and a copy thereof returned to applicant(s).

It is hereby stated that no item of information contained in the Information Disclosure Statement was cited in a patent office in a counterpart application, and, to the knowledge of the undersigned, after making reasonable inquiry, no item of information contained in the Information Disclosure Statement was known to any individual associated with the filing or prosecution of the subject application more than three months prior to the filing of the Information Disclosure Statement.

The references were cited in a Search Report dated September 27, 2005 (copy enclosed herewith) in a counterpart PCT application.

The submission of this Information Disclosure Statement is not to be construed as a representation that a search has been made in the subject application and is not to be construed as an admission that the information cited in this statement is material to patentability.

Please charge any fees due to Deposit Account 02-2666. A duplicate copy of the Fee Transmittal (PTO/SB/17) is enclosed for this purpose.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Date: October 26, 2005

Vincent H. Anderson, Reg. No. 54,962

12400 Wilshire Boulevard, 7th Floor Los Angeles, CA 90025

Telephone: (503) 439-8778

I hereby certify that this correspondence is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Theresa Belland

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Date

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Substitute for form 1449A/PTO

STATEMENT BY APPLICANT

(use as many sheets as necessary)

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Sheet | of

	Complete if Known	
Application Number	10/812,464	
Filing Date	March 29, 2004	
First Named Inventor	John P. Barnak	_
Art Unit	2823	
Examiner Name	William M. Brewster	
Attorney Docket Number		

		U.S. PATE	NT DOCUMENTS		
Examiner Cite	Document Number Number - Kind Code² (if known)	Publication Date or Issue Date	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant	
Initials* No.	:	MM-DD-YYYY	Applicant of Gited Document	Figures Appear	
	US-2003/06001 A1	03-27-2003	Madhav et al.		
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	FOREIGN PATENT DOCUMENTS						
Examiner	Cite	Foreign Patent Document			Pages, Columns, Lines,		
Initials*	No.1	Country Code - Number - Kind Code (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Where Relevant Passages or Relevant Figures Appear		
	<u> </u>	EP 0359228 A	03-21-1990	National Semiconductor			
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Examiner	Date
Signature	Considered

Based on PTO/SB/08A (08-03) as modified by Blakely, Solokoff, Taylor & Zafman (wlr) 08/11/2003.

^{*}Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

^{&#}x27;Applicant's unique citation designation number (optional)!See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04:Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3):For Japanese patent documents, the indication of the year of reign of the Emperor must precede the serial number of the patent document. 'Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possibl@Applicant is to place a check mark here if English language Translation is attached.

Substitute fo	r form 1449A/PTO			Complete if Known		
INFOR	MATION	DISCL OS	LIDE	Application Number	10/812,464	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Filing Date	March 29, 2004	
				First Named Inventor	John P. Barnak	
				Art Unit	2823	
		1 1		Examiner Name	William M. Brewster	
Sheet	2	of	2	Attorney Docket Number	42P19017	

		NON PATENT LITERATURE DOCUMENTS	
Examiner Initials*	Cite No.'	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		Patent Abstracts of Japan, Publication No. 2000195885, July 14, 2000, Applicant: Fujitsu Ltd.	
		KWANG-LUNG LIN ET AL., "The Interdiffusion and the Feasibility of Al/Mo/Ni/(Pb-Sn) as a Solder Bump System", <i>Thin Solid Films</i> , February 28, 1997, pp. 218-223, Vol. 295, No. 1-2, Elsevier-Sequoia S.A., Lausanne, Switzerland.	
		KWANG-LUNG LIN ET AL., "Material Interactions of Solder Bumps Produced With Fluxless Wave Soldering", <i>IEEE Transactions on Components, Packaging, and Manufacturing TechnologyPart B</i> , February 1998, pp. 59-64, Vol. 21, No. 1,	
		KEN'ICHI MIZUISHI ET AL., "Thermal Stability of Various Ball-Limited-Metal Systems Undder Solder Bumps", <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> , December 1988, pp. 481-484, Vol. 11, No. 4.	
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Examiner	. Date
Signature	Considered

*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

'Applicant's unique citation designation number? Applicant is to place a check mark here if English language Translation is attached.